

4.5Ω Dual Bilateral SPST Analog Switch

1 FEATURES

- **Bandwidth: 300MHz**
- **High Speed, Typically 30ns**
- **Supply Range: +1.8V to +5.5V**
- **Low ON-State Resistance: 4.5Ω(TYP)**
- **Rail-to-Rail Operation**
- **TTL/CMOS Compatible**
- **Extended Industrial Temperature Range: -40°C to +125°C**
- **Packages: DFN2X3-8, MSOP8**

2 APPLICATIONS

- **Wireless Devices**
- **Audio and Video Signal Routing**
- **Portable Computing**
- **Wearable Devices**
- **Signal Gating, Chopping, Modulation or Demodulation (Modem)**
- **Cell Phones**

3 DESCRIPTIONS

The RS2266 is a bidirectional 2-channel single-pole single-throw (SPST) analog switch, which is designed to operate from 1.8V to 5.5V.

The RS2266 device can handle both analog and digital signals. It features bandwidth(300MHz) and low on-resistance (4.5Ω TYP).

Each switch section has its own enable-input control (SEL). A high-level voltage applied to SEL turns on the associated switch section.

Applications include signal gating, chopping, modulation or demodulation (modem), and signal multiplexing for analog-to-digital and digital-to-analog conversion systems.

Device Information ⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE(NOM)
RS2266	MSOP8	3.00mm×3.00mm
	DFN2X3-8	2.00mm×3.00mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

4 FUNCTIONAL DIAGRAMS OF RS2266

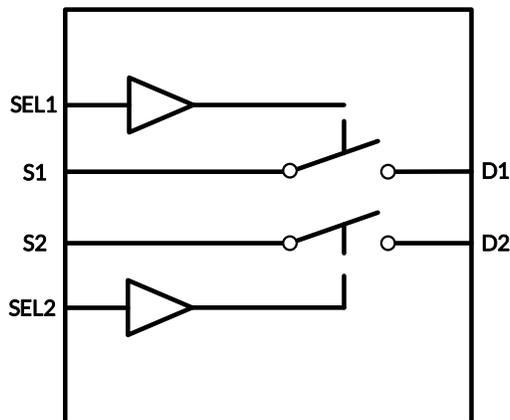


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5 REVISION HISTORY

Note: Page numbers for previous revisions may differ from page numbers in the current version.

VERSION	Change Date	Change Item
A.1	2019/11/22	Initial version completed
A.2	2020/08/12	Change "Package Qty" in ordering information table for production management.
A.3	2020/12/13	Add DFN2X3-8 Package, remove SOIC8 Package
A.3.1	2024/03/08	1. Added the TAPE AND REEL INFORMATION 2. Modify packaging naming
A.4	2024/05/07	1. Add MSL on Page 5 in RevA.3.1 2. Add Package thermal impedance on Page 4 in RevA.3.1 3. Update PACKAGE note
A.5	2024/12/24	1. Delete t_{BBM} PARAMETER and test charts 2. Modify the test chart for Turn-On (t_{ON}) and Turn-Off Time (t_{OFF}) 3. Modify PIN CONFIGURATIONS 4. Modify DFN2X3-8 PACKAGE OUTLINE DIMENSIONS

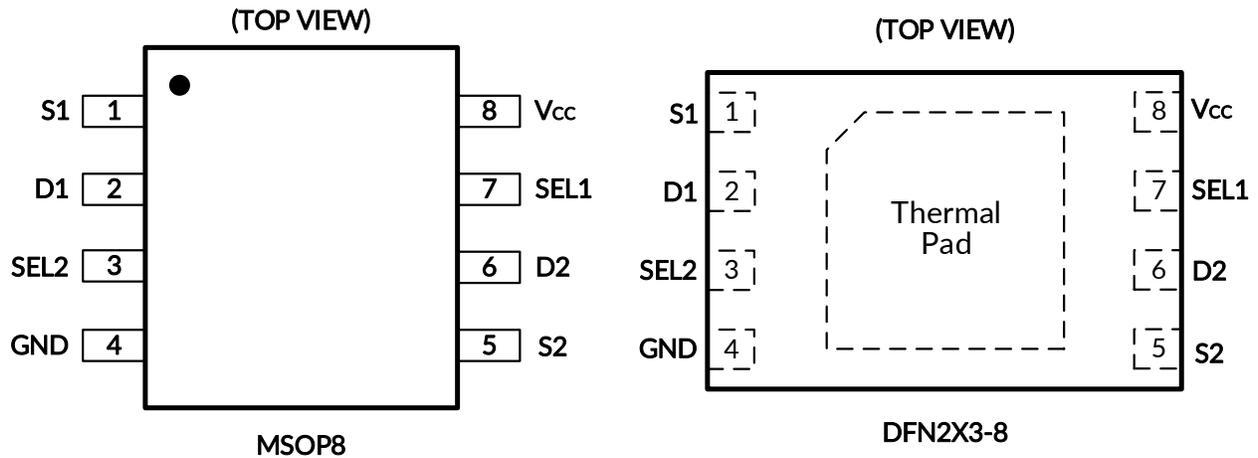
6 PACKAGE/ORDERING INFORMATION ⁽¹⁾

PRODUCT	ORDERING NUMBER	TEMPERATURE RANGE	PACKAGE LEAD	PACKAGE MARKING ⁽²⁾	MSL ⁽³⁾	PACKAGE OPTION
RS2266	RS2266XM	-40°C ~+125°C	MSOP8	RS2266	MSL3	Tape and Reel, 4000
	RS2266XTDB8-B	-40°C ~+125°C	DFN2X3-8	2266B	MSL3	Tape and Reel, 3000

NOTE:

- (1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.
- (2) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.
- (3) Runic classify the MSL level with using the common preconditioning setting in our assembly factory conforming to the JEDEC industrial standard J-STD-20F, Please align with Runic if your end application is quite critical to the preconditioning setting or if you have special requirement.

7 PIN CONFIGURATIONS



7.1 Pin Description

NAME	PIN	I/O	DESCRIPTION
S1	1	I/O	Bidirectional signal to be switched
D1	2	I/O	Bidirectional signal to be switched
SEL2	3	I	Controls the switch (L = OFF, H = ON)
GND	4	-	Ground
S2	5	I/O	Bidirectional signal to be switched
D2	6	I/O	Bidirectional signal to be switched
SEL1	7	I	Controls the switch (L = OFF, H = ON)
Vcc	8	-	Power Supply
Thermal Pad	-	-	Connect thermal pad to GND

(1) I = Input, O = Output.

7.2 Function Table

SELECT INPUTS	SWITCH STATUS
SEL1/SEL2	
High	All Switches ON
Low	All Switches OFF

NOTE: Input and output pins are identical and interchangeable. Any may be considered an input or output; signals pass equally well in both directions.

8 SPECIFICATIONS

8.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

SYMBOL	PARAMETER		MIN	MAX	UNIT
V _{CC}	Supply Voltage ⁽²⁾		-0.3	6.0	V
V _{IN}	Input Voltage ^{(2) (3)}		-0.3	6.0	
V _O	Switch I/O Voltage ^{(2) (3) (4)}		-0.3	V _{CC} +0.3	
I _{IK}	Control input clamp current	V _I <0		-50	mA
I _{I/OK}	I/O port diode current	V _{I/O} < 0 or V _{I/O} > V _{CC}		-50	
I _T	On-state switch current	V _{IO} =0 to V _{CC}	-50	50	
	Continuous current through V _{CC} or GND		-100	100	
θ _{JA}	Package thermal impedance ⁽⁵⁾	MSOP8		170	°C/W
		DFN2X3-8		215	
T _J	Junction Temperature ⁽⁶⁾		-40	150	°C
T _{stg}	Storage temperature		-65	150	

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) All voltages are with respect to ground, unless otherwise specified.

(3) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

(4) This value is limited to 5.5 V maximum.

(5) The package thermal impedance is calculated in accordance with JESD-51.

(6) The maximum power dissipation is a function of T_{J(MAX)}, R_{θJA}, and T_A. The maximum allowable power dissipation at any ambient temperature is P_D = (T_{J(MAX)} - T_A) / R_{θJA}. All numbers apply for packages soldered directly onto a PCB.

8.2 ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-Body Model (HBM)	±2000	V
		Machine Model (MM)	±300	V



ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

SYMBOL	PARAMETER	MIN	MAX	UNIT
V _{CC}	Supply Voltage	1.8	5.5	V
T _A	Operating temperature	-40	+125	°C

8.4 Electrical Characteristics

$V_{CC} = 5.0\text{ V}$ or 3.3 V , FULL = -40°C to $+125^{\circ}\text{C}$, Typical values are at $T_A = +25^{\circ}\text{C}$. (unless otherwise noted)

PARAMETER	SYMBOL	CONDITIONS	V_{CC}	T_A	MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾	UNIT
ANALOG SWITCH								
Analog Signal Range	V_S, V_D			FULL	0		V_{CC}	V
On-Resistance	R_{ON}	$V_S = V_{CC} / 2$, $I_{SD} = -10\text{mA}$, Switch ON, See Figure 4	5V	+25°C		4.5	8	Ω
				FULL			8.5	Ω
			3.3V	+25°C		7	10	Ω
				FULL			10.5	Ω
On-Resistance Match Between Channels	ΔR_{ON}	$V_S = V_{CC} / 2$, $I_{SD} = -10\text{mA}$, Switch ON, See Figure 4	5V	+25°C		0.15	0.3	Ω
				FULL			0.4	Ω
			3.3V	+25°C		0.15	0.3	Ω
				FULL			0.4	Ω
On-Resistance Flatness	$R_{FLAT(ON)}$	$0 \leq (V_S) \leq V_{CC} / 2$, $I_{SD} = -10\text{mA}$, Switch ON, See Figure 4	5V	+25°C		2	3	Ω
				FULL			3.3	Ω
			3.3V	+25°C		3	4	Ω
				FULL			4.3	Ω
Source, Drain OFF Leakage Current	$I_{D(OFF)}, I_{S(OFF)}$	$V_D = 0.3\text{V}, V_{CC} / 2, V_S = V_{CC} / 2$, 0.3V See Figure 5	1.8 to 5.5V	FULL			1	μA
Channel ON Leakage Current	$I_{D(ON)}, I_{S(ON)}$	$V_D = 0.3\text{V}$, Open $V_S = \text{Open}$, 0.3V See Figure 6	1.8 to 5.5V	FULL			1	μA
DIGITAL CONTROL INPUTS ⁽¹⁾								
Input High Voltage	V_{IH}		5V	FULL	1.5			V
			3.3V	FULL	1.3			V
Input Low Voltage	V_{IL}		5V	FULL			0.6	V
			3.3V	FULL			0.5	V
Input Leakage Current	I_{IN}	$V_{IN} = V_{IO}$ or 0	1.8 to 5.5V	FULL			1	μA

(1) All unused digital inputs of the device must be held at V_{IO} or GND to ensure proper device operation.

(2) Limits are 100% production tested at 25°C . Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.

(3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.

Electrical Characteristics (continued)

V_{CC} = 5.0 V or 3.3V, FULL = -40°C to +125°C, Typical values are at T_A = +25°C (unless otherwise noted)

PARAMETER	SYMBOL	CONDITIONS	V _{CC}	T _A	MIN	TYP	MAX	UNIT
DYNAMIC CHARACTERISTICS								
Turn-On Time	t _{ON}	V _S = V _{CC} , R _L = 300Ω, C _L = 35pF, See Figure 7	5V	+25°C		30		ns
			3.3V			40		
Turn-Off Time	t _{OFF}	V _S = V _{CC} , R _L = 300Ω, C _L = 35pF, See Figure 7	5V	+25°C		25		ns
			3.3V			30		
-3dB Bandwidth	BW	Switch ON, R _L = 50Ω, See Figure 8	5V	+25°C		300		MHz
Off Isolation	O _{ISO}	R _L = 50Ω, Switch OFF, See Figure 9		+25°C		-52		dB
				+25°C		-71		dB
Source, Drain OFF Capacitance	C _{S(OFF)} , C _{D(OFF)}	V _S = V _{CC} / 2 or GND, Switch OFF		+25°C		5		pF
Source, Drain ON Capacitance	C _{S(ON)} , C _{D(ON)}	V _S = V _{CC} / 2 or GND, Switch ON		+25°C		15		pF
POWER REQUIREMENTS								
Power Supply Range	V _{CC}			FULL	1.8		5.5	V
Power Supply Current	I _{CC}	V _{IN} = GND or V _{CC}	5.5V	FULL			1	μA

8.5 Typical Characteristics

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

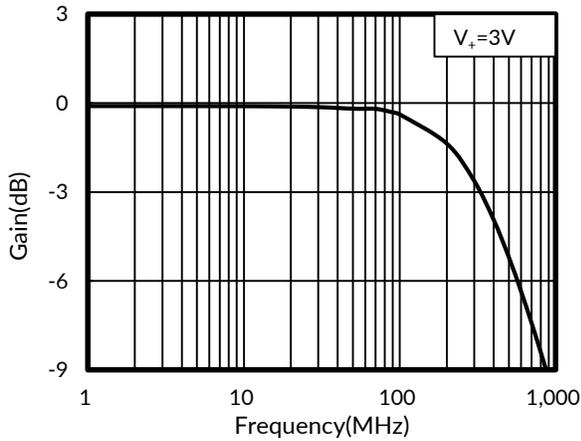


Figure 1. Bandwidth vs Frequency

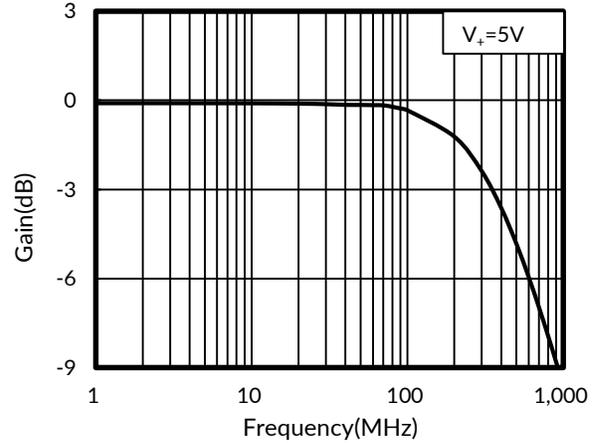


Figure 2. Bandwidth vs Frequency

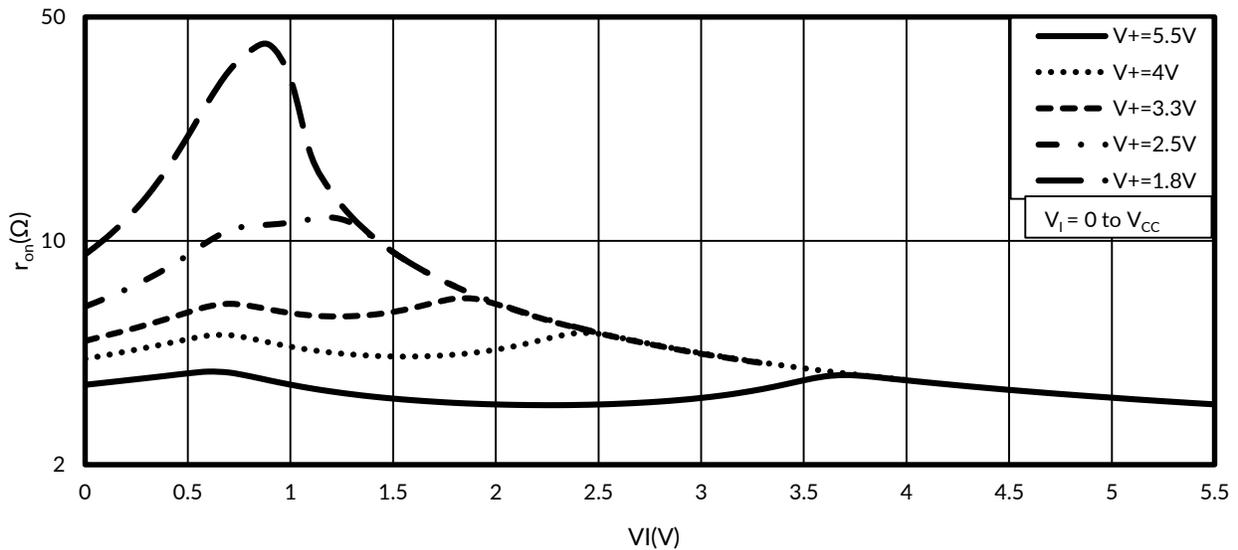


Figure 3. Typical r_{on} as a Function of Input Voltage

9 PARAMETER MEASUREMENT INFORMATION

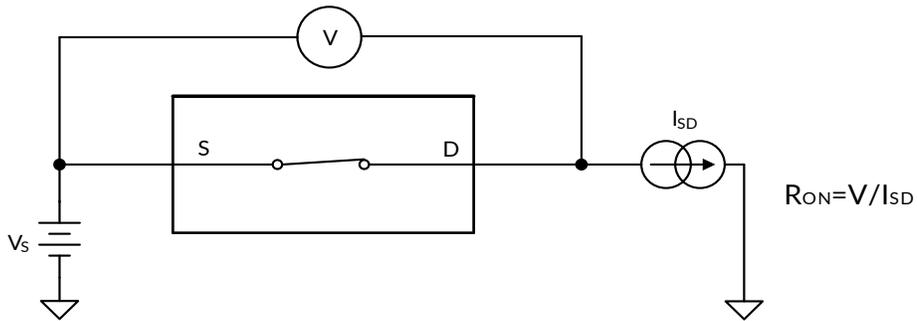


Figure 4. ON-State Resistance (R_{ON})

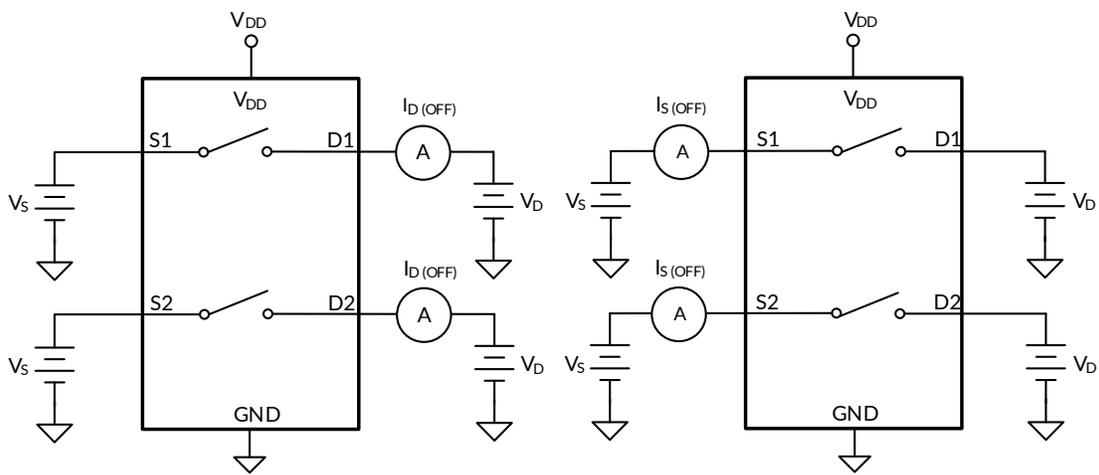


Figure 5. OFF-State Leakage Current ($I_{D(OFF)}$, $I_{S(OFF)}$)

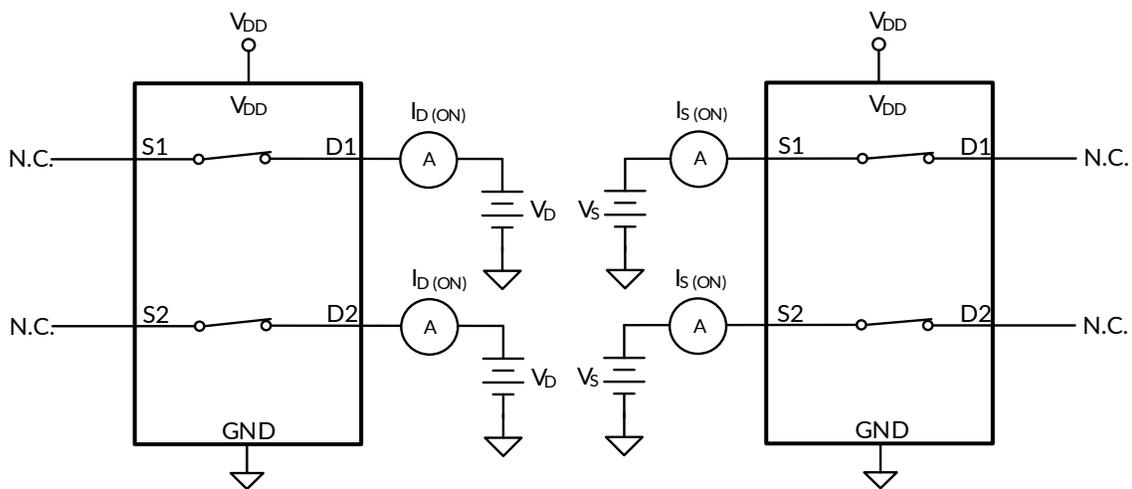


Figure 6. ON-State Leakage Current ($I_{D(ON)}$, $I_{S(ON)}$)

PARAMETER MEASUREMENT INFORMATION (continued)

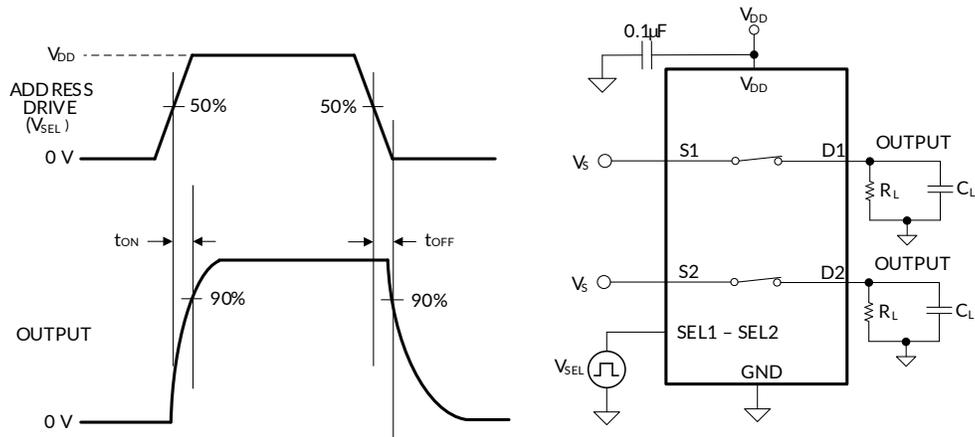


Figure 7. Turn-On (t_{ON}) and Turn-Off Time (t_{OFF})

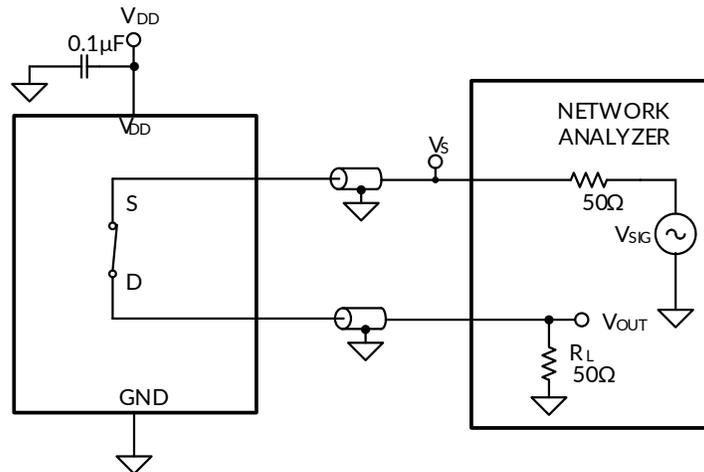


Figure 8. Bandwidth (BW)

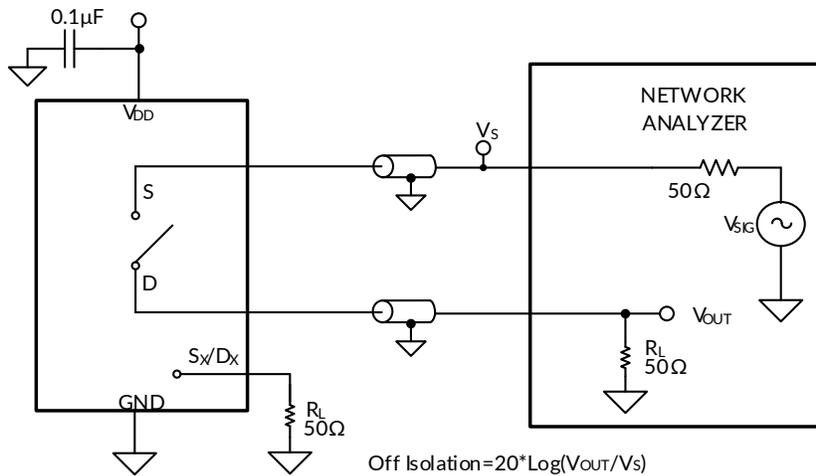
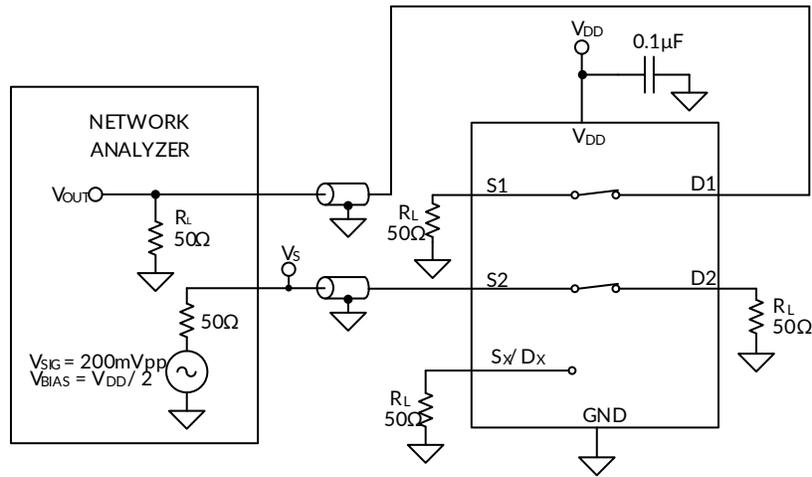


Figure 9. OFF Isolation (O_{iso})

PARAMETER MEASUREMENT INFORMATION(continued)



Channel-to-Channel Crosstalk = $20 \cdot \log(V_{out}/V_s)$

Figure 10. Crosstalk (XTALK)

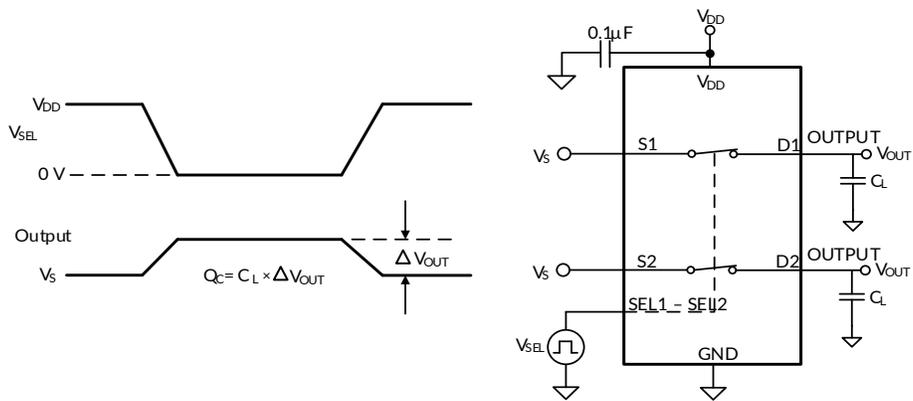


Figure 11. Charge Injection (Qc)

10 TYPICAL APPLICATION

The RS2266 can be used in any situation where a Dual SPST switch would be used and a solid-state, voltage-controlled version is preferred. The RS2266 allows on/off control of analog and digital signals with a digital control signal. All input signals should remain between 0V and V_{CC} for optimal operation.

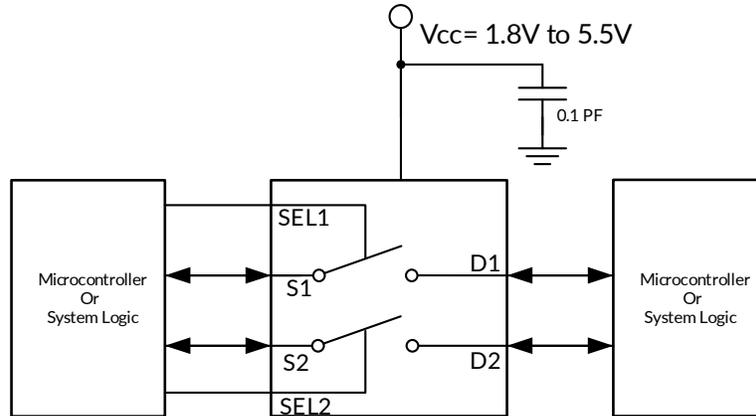
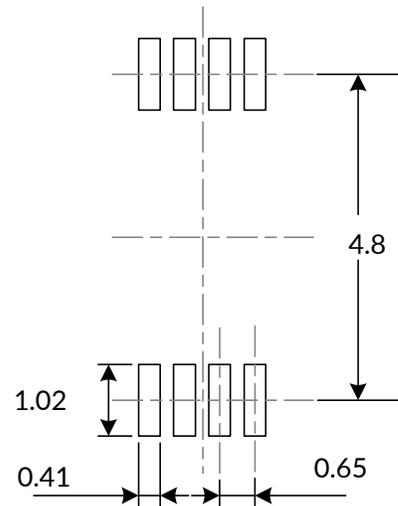
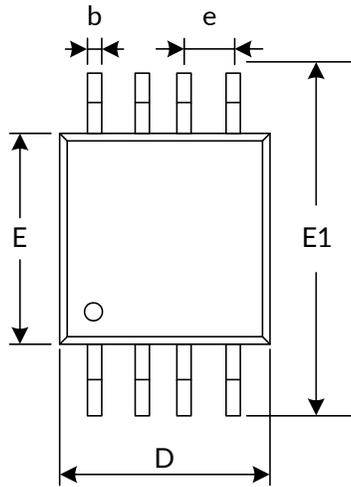


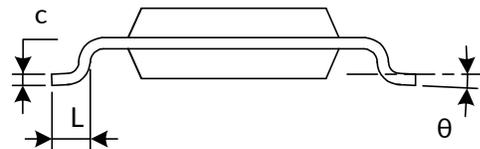
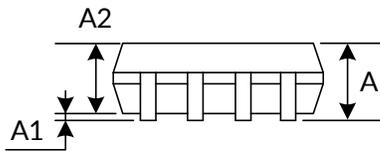
Figure 12. Typical Application Schematic

11 PACKAGE OUTLINE DIMENSIONS

MSOP8⁽³⁾



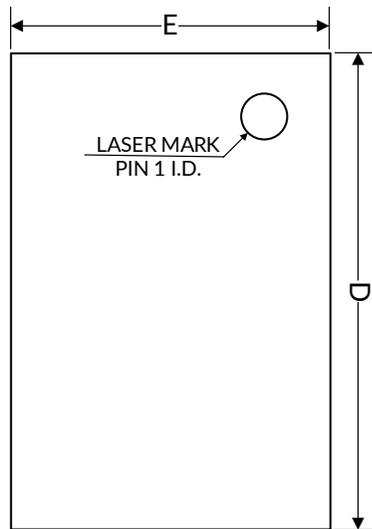
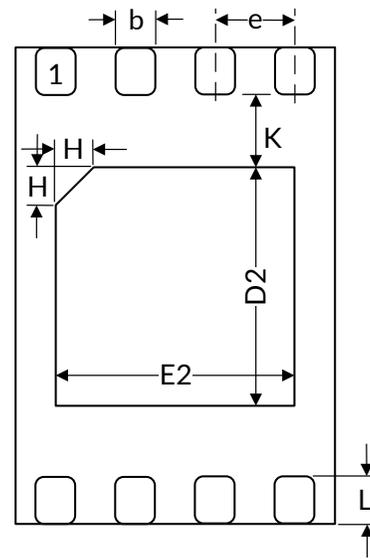
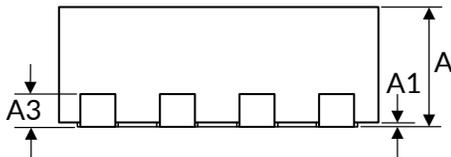
RECOMMENDED LAND PATTERN (Unit: mm)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	0.820	1.100	0.032	0.043
A1	0.020	0.150	0.001	0.006
A2	0.750	0.950	0.030	0.037
b	0.250	0.380	0.010	0.015
c	0.090	0.230	0.004	0.009
D ⁽¹⁾	2.900	3.100	0.114	0.122
e	0.650(BSC) ⁽²⁾		0.026(BSC) ⁽²⁾	
E ⁽¹⁾	2.900	3.100	0.114	0.122
E1	4.750	5.050	0.187	0.199
L	0.400	0.800	0.016	0.031
θ	0°	6°	0°	6°

NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

DFN2X3-8⁽³⁾

TOP VIEW

BOTTOM VIEW

SIDE VIEW

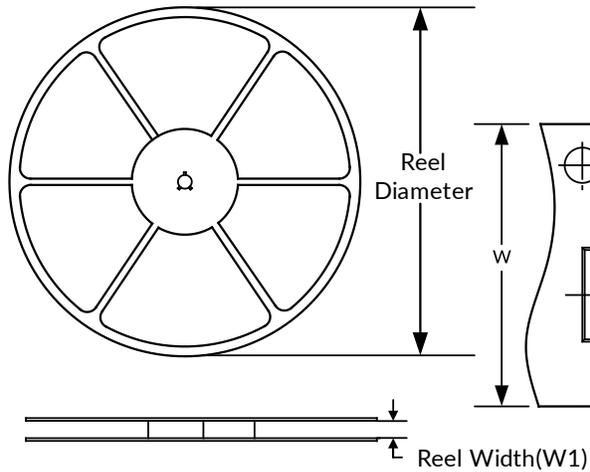
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	0.700	0.800	0.028	0.032
A1	0.000	0.050	0.000	0.002
A3	0.203 REF ⁽²⁾		0.008 REF ⁽²⁾	
b	0.200	0.300	0.008	0.012
D ⁽¹⁾	2.930	3.070	0.115	0.121
E ⁽¹⁾	1.930	2.070	0.076	0.082
D2	1.400	1.600	0.055	0.063
E2	1.400	1.600	0.055	0.063
e	0.400	0.600	0.016	0.024
H	0.250 REF ⁽²⁾		0.010 REF ⁽²⁾	
K	0.200	-	0.008	-
L	0.230	0.370	0.009	0.015

NOTE:

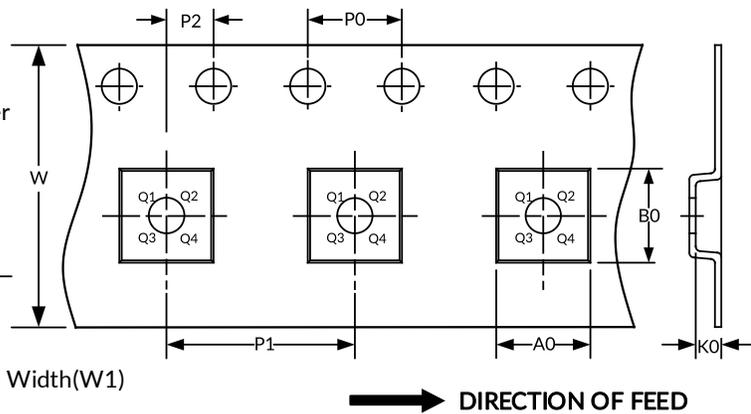
1. Plastic or metal protrusions of 0.075mm maximum per side are not included.
2. REF is the abbreviation for Reference.
3. This drawing is subject to change without notice.

12 TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSION



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width(mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
MSOP8	13"	12.4	5.20	3.30	1.50	4.0	8.0	2.0	12.0	Q1
DFN2X3-8	7"	9.5	2.30	3.30	0.95	4.0	4.0	2.0	8.0	Q2

NOTE:

1. All dimensions are nominal.
2. Plastic or metal protrusions of 0.15mm maximum per side are not included.

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